## ABSTRACT OF THE DISCLOSURE

A semiconductor chip 2 is disposed within a device hole as formed in a tape base material 1a of a tape carrier 1, which chip is less in thickness than the tape base material 1a, while sealing by a seal resin 3 to permit both the principal surface and back surface of such semiconductor chip 2 to be coated therewith. And, let the position of the semiconductor chip 2 in a direction along the thickness of the tape base 1a be identical to a stress neutral plane of the TCP as a whole.